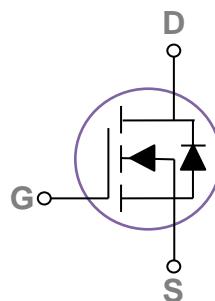


**General Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

**SOT23-3S Pin Configuration**

BVDSS	RDS(ON)	ID
30V	24mΩ	6.5A

**Features**

- 30V, 6.5A, RDS(ON) = 24mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

**Applications**

- MB / VGA / Vcore
- Load Switch
- Hand-Held Instrument

**Absolute Maximum Ratings** Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>A</sub> =25°C)	6.5	A
	Drain Current – Continuous (T <sub>A</sub> =100°C)	4.1	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	26	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	32	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	8	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	1.56	W
	Power Dissipation – Derate above 25°C	0.012	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	80	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
$I_{\text{DS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	20	24	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=4\text{A}$	---	27	34	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-4	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=4\text{A}$	---	6.5	---	S

**Dynamic and switching Characteristics**

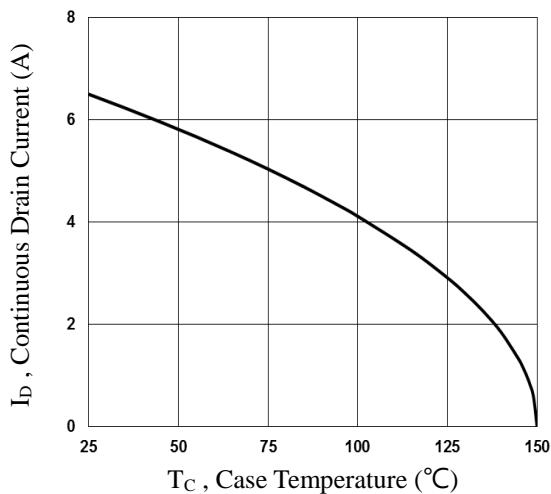
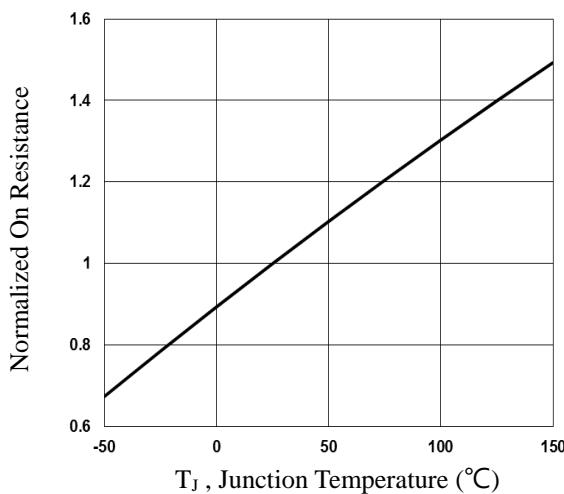
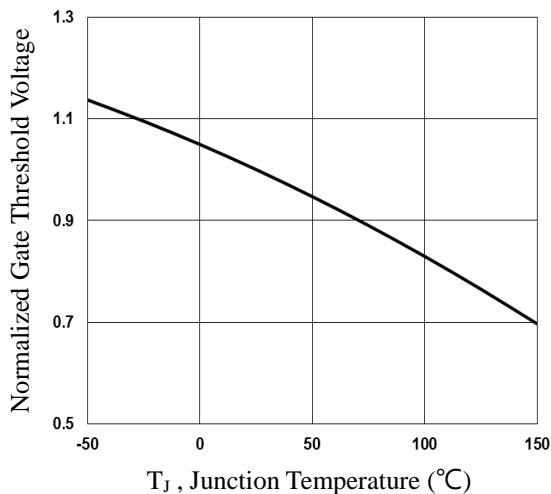
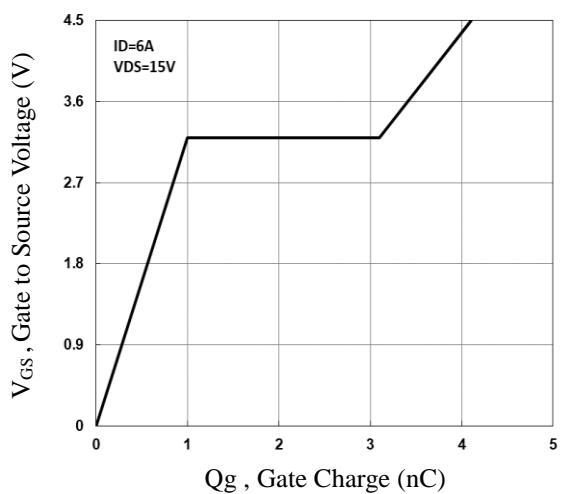
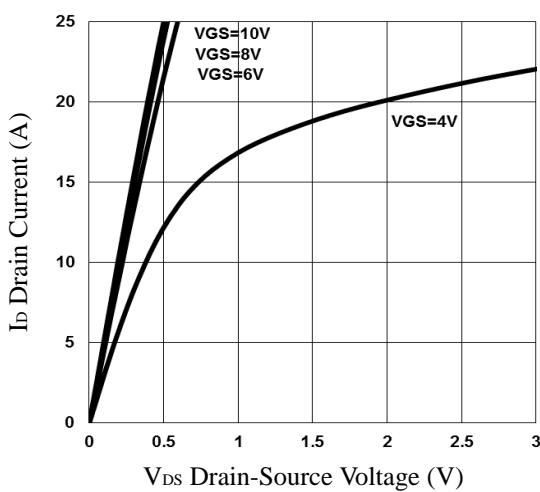
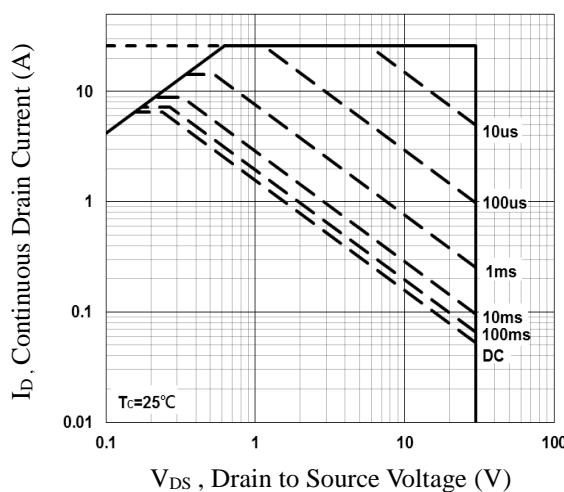
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=6\text{A}$	---	4.1	8	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	1	2	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	2.1	4	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$	---	2.8	5	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	7.2	14	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	15.8	30	
$T_f$	Fall Time <sup>3, 4</sup>		---	4.6	9	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	345	500	pF
$C_{\text{oss}}$	Output Capacitance		---	55	80	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	32	45	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	3.2	6.4	$\Omega$

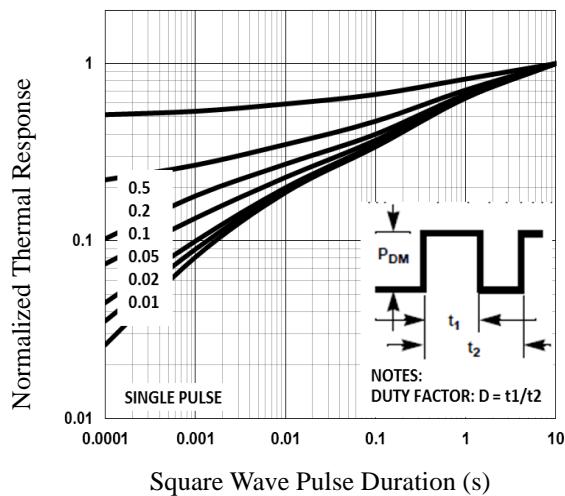
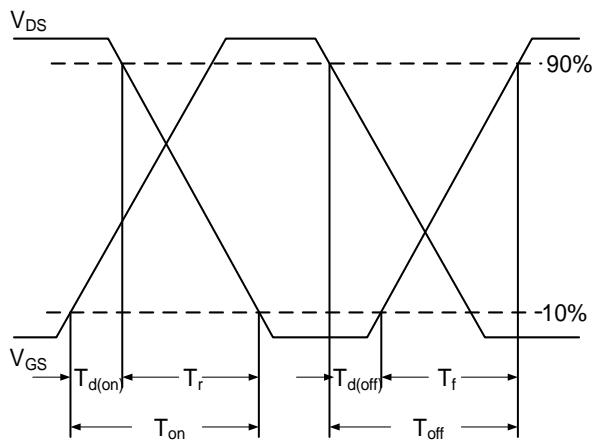
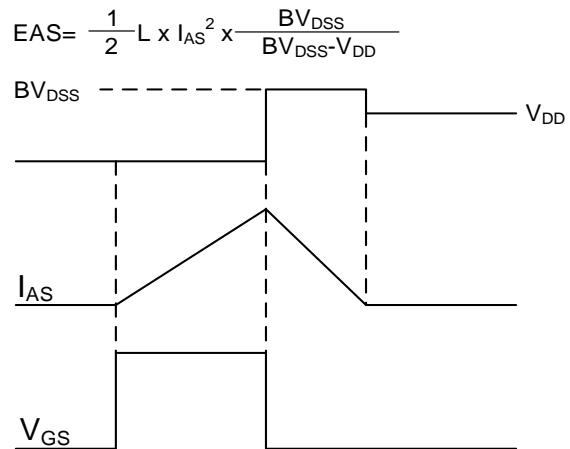
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	6.5	A
$I_{\text{SM}}$	Pulsed Source Current <sup>3</sup>		---	---	26	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time		---	---	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	---	---	nC

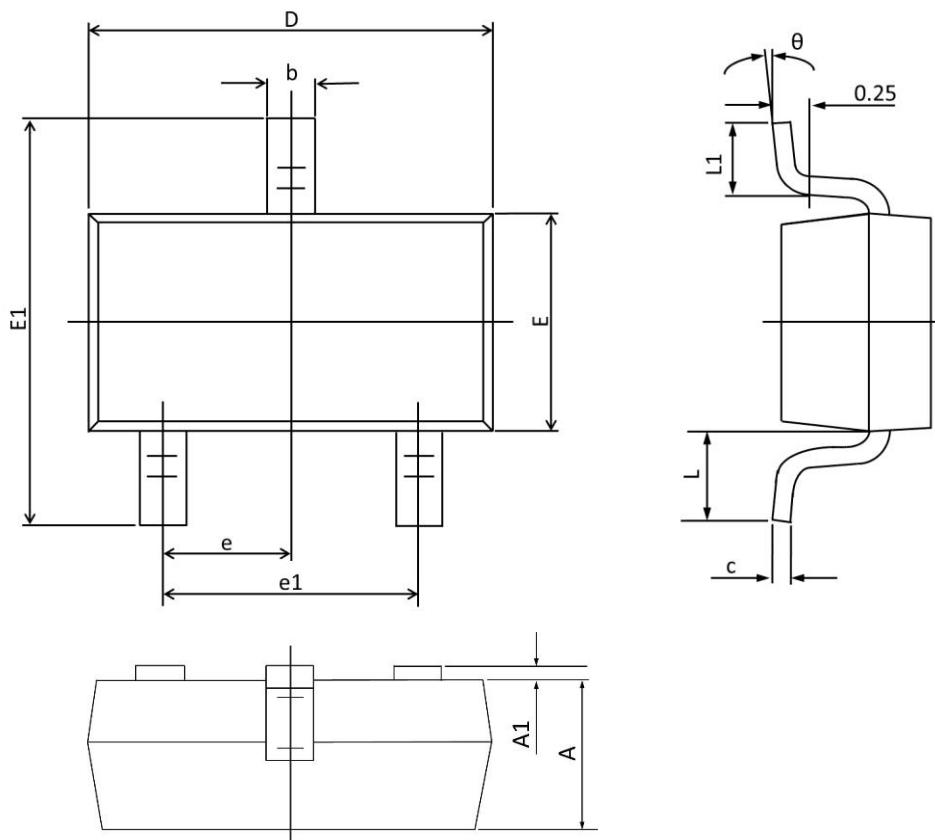
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=1\text{mH}$ ,  $I_{\text{AS}}=8\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

**Fig.1 Continuous Drain Current vs.  $T_C$** **Fig.2 Normalized RD<sub>SON</sub> vs.  $T_J$** **Fig.3 Normalized  $V_{th}$  vs.  $T_J$** **Fig.4 Gate Charge Waveform****Fig.5 On Region Characteristics****Fig.6 Maximum Safe Operation Area**

**Fig.7 Normalized Transient Response****Fig.8 Switching Time Waveform****Fig.9 EAS Waveform**

## SOT23-3S PACKAGE INFORMATION



<b>Symbol</b>	<b>Dimensions In Millimeters</b>		<b>Dimensions In Inches</b>	
	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>
A	<b>0.900</b>	<b>1.150</b>	<b>0.035</b>	<b>0.045</b>
A1	<b>0.001</b>	<b>0.100</b>	<b>0.000</b>	<b>0.004</b>
b	<b>0.300</b>	<b>0.500</b>	<b>0.012</b>	<b>0.020</b>
c	<b>0.080</b>	<b>0.180</b>	<b>0.003</b>	<b>0.008</b>
D	<b>2.700</b>	<b>3.100</b>	<b>0.106</b>	<b>0.122</b>
E	<b>1.100</b>	<b>1.500</b>	<b>0.043</b>	<b>0.059</b>
E1	<b>2.100</b>	<b>2.640</b>	<b>0.080</b>	<b>0.104</b>
e	<b>0.950 TYP.</b>		<b>0.037 TYP.</b>	
e1	<b>1.780</b>	<b>2.040</b>	<b>0.070</b>	<b>0.080</b>
L	<b>0.550 REF.</b>		<b>0.022 REF.</b>	
L1	<b>0.100</b>	<b>0.500</b>	<b>0.004</b>	<b>0.020</b>
theta	<b>1°</b>	<b>10°</b>	<b>1°</b>	<b>10°</b>